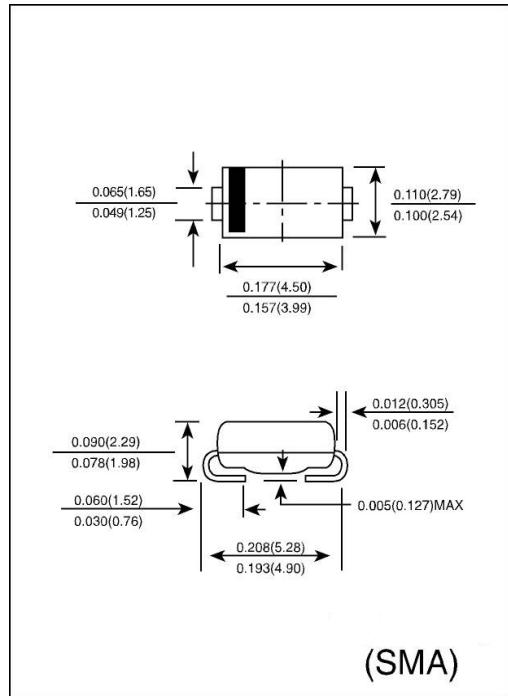


FEATURES

- Glass passivated chip junction
- Ideal for surface mounted applications
- Low leakage
- High forward surge current capability.
- High temperature soldering guaranteed:
260°C/10 seconds at terminals.

MECHANICAL DATA

- Case: Transfer molded plastic
- Epoxy: UL94V - 0 rate flame retardant.
- Polarity: Color band denotes cathode end
- Lead: Plated terminals solderable per MIL - STD - 202E method 208C
- Weight: 0.002 ounce, 0.057 gram



(SMA)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25°C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load.
- For capacitive load derate current by 20%

Catalog Number	SYMBOLS	1N4007	UNITS
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	1000	Volts
Maximum RMS Voltage	V _{RMS}	700	Volts
Maximum DC Blocking Voltage	V _{DC}	1000	Volts
Maximum Average Forward Rectified Current, at T _A = 75°C	I _(AV)	1.0	Amp
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30	Amps
Maximum Instantaneous Forward Voltage Drop at 1.0A	V _F	1.1	Volts
Maximum DC Reverse Current at rated DC blocking voltage	I _R	5.0 50	µA
Maximum Full Load Reverse Current, full cycle average at T _A = 75°C	I _{R(AV)}	30	µA
Typical Junction Capacitance (Note 1)	C _J	15	pF
Typical Thermal Resistanc (Note 2)	R _{θJA}	75	°C/w
Operating and Storage Temperature Range	T _J , T _{STG}	(-65 to +175)	°C

NOTES:

1. Measured at 1.0 MHz and applied average voltage of 4.0 volts.

2. 6.0 X 6.0mm² copper pads to each terminal.

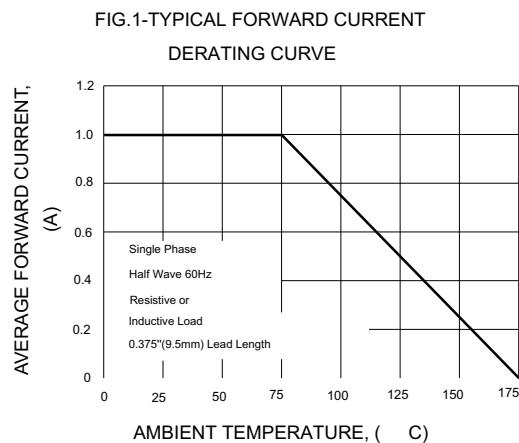


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

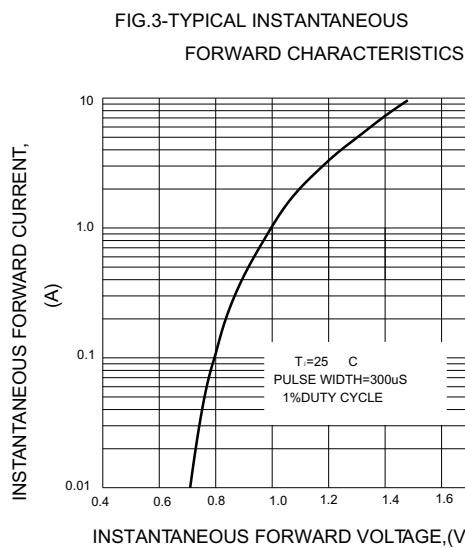
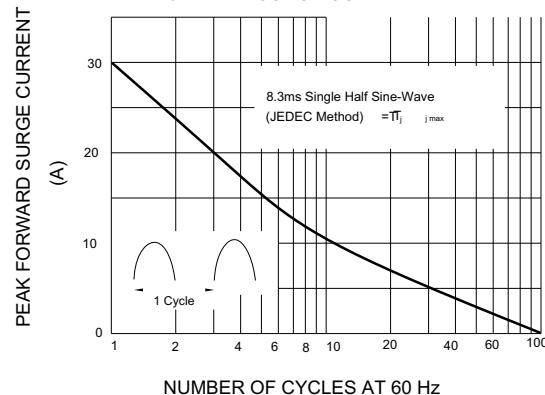


FIG.4-TYPICAL REVERSE CHARACTERISTICS

